Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model
[List multiple models if applicable.]

- HP 6360t Mobile Thin Client
- Name / Model #2
- Name / Model #3
- Name / Model #4
- Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Yes</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
Components, parts and materials containing radioactive substances | No | 0

2.0 Tools Required
List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>T8 Torx</td>
<td>T8</td>
</tr>
<tr>
<td>Cross</td>
<td>#1</td>
</tr>
<tr>
<td>Nipper</td>
<td>#1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Slide out the battery and door
2. Take out thermal / HDD /ODD modules
3. Slide out Keyboard.
4. Take out Lower case.
5. Take out Mother board, Express board and Display.
6. Tear down LCD bezel
7. Tear down LCD
8. ...

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Nena machine teardown report

ME : Hank Wu
Data : 2011/05/04
Step 1: Slide out the battery and door

1. Release Battery latch as PIC1 and slide out the battery.
2. Release door latch as PIC2 and slide out the door
Step2: Take out thermal / HDD /ODD modules

1. Take out Fan by unscrewing screws. (No1~No2)
2. Take out heat sink by unscrewing screws(No3~No6)
3. Slide and take out HDD module after release screws (No7~No9)
4. Slide out the ODD module after release screw ( No10)
**Step 3**: Slide out Keyboard

1. Unscrew 4 keyboard screw on bottom side. (No1~No4)
2. Slide and take out the keyboard module.

![Image of keyboard module and hands typing]

Hole for user to put keyboard to release hook
Step4  (1/2): Take out Lower case

1. Unscrew 1 screw on upper case and release all cable. (No1)
2. Unscrew real side 4 screws (No2-No5)
Step 4 (2/2): Take out Lower case

1. Unscrewing all screw on bottom side (No1~No11)
2. Release the speaker connector (A)
Step 5: Take out Mother board, Express board and Display

1. Take out Express board by unscrewing 3 screws (No1~No3)
2. Take out PCBA by unscrewing 3 screws (No4~No6)
3. Take out Display module by unscrewing 2 screws. (No7~No8)
Step 6: Tear down LCD bezel

1. Tear down LCD Mylar (A)

2. Unscrew 2 screws and tear down LCD bezel (follow read arrow direction)
Step 1/2: Tear down LCD

1. Tear down LCD assembly by unscrewing 6 screws (No1~No6)
Step 2/2: Tear down LCD

1. Tear down LCD assembly by unscrewing 6 screws (No1~No6)